

INFORMATION DISCLOSURE CITATION			ATTY. DOCKET NO. 8003-370		SERIAL NO. 09/624,712		
PTO-14497			APPLICANT Jae Heon Park				
APR 05 2002			FILING DATE 7/25/2000		GROUP 1756		
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
KAD	5,885,755	3/23/1999	Nakagawa, et al.	430	325	4/29/1998	
KAD	5,342,738	8/30/1994	Ikeda	430	325	6/4/1992	
KAD	6,159,662	12/12/2000	Chen, et al.	430	313	5/17/1999	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
KAD	WO 00/16163	23/3/2000	PCT	G03F	7/30	<input type="checkbox"/>	<input type="checkbox"/>
KAD	WO 99/53381	21/10/1999	PCT	G03F	7/32	<input type="checkbox"/>	<input type="checkbox"/>
KAD	EP 0794463 A2	10/9/1997	EPO	G03F	7/30	<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
KAD	Zama Shigenori; Method for Developing Photoresist; Patent Abstracts of Japan; Publication No. 09297403; Publication Date 18/1/1997; Applicant: Nittetsu Semiconductor KK; Int. Cl. G03F 7/30						
KAD	Hagi Toshio; Method for Developing Photoresist; Patent Abstracts of Japan; Publication No.: 07142344; Publication Date 02/06/1995; Applicant: Matsushita Electric Ind. Co. Ltd, Int. Cl. H01L 21/027						
KAD	Miyamoto Koichi; Developing Device; Patent Abstracts of Japan; Publication No. 58088749; Publication Date 26/05/1983; Applicant: Hitachi Tokyo Electronics Co. Ltd., Int. Cl. G03F 7/00						
KAD	Nishikata Eiji; Developing Method of Resist Film; Patent Abstracts of Japan; Publication No.: 59050440; Publication Date: 23/03/1984; Applicant: Fujitsu, Ltd., Int. Cl. G03C 5/24						
EXAMINER	K. Duda		DATE CONSIDERED		5-20-02		

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.